

Docket No.: 67161-134

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of	:	Customer Number: 20277
	:	
Koyu ASAI, et al.	:	Confirmation Number:
	:	
Serial No.:	:	Group Art Unit:
	:	
Filed: December 03, 2003	:	Examiner: Unknown
	:	
For:		INTERCONNECTION STRUCTURE OF SEMICONDUCTOR DEVICE

INFORMATION DISCLOSURE STATEMENT

Mail Stop IDS
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In accordance with the provisions of 37 C.F.R. 1.56, 1.97 and 1.98, the attention of the Patent and Trademark Office is hereby directed to the documents listed on the attached form PTO-1449. It is respectfully requested that the documents be expressly considered during the prosecution of this application, and that the documents be made of record therein and appear among the "References Cited" on any patent to issue therefrom.

This Information Disclosure Statement is being filed within three months of the U.S. filing date OR before the mailing date of a first Office Action on the merits. No certification or fee is required.

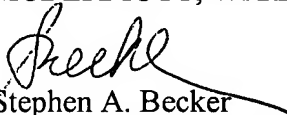
The relevance of the references listed on attached Form 1449 is discussed in the present specification.

Serial No.:

Please charge any shortage in fees due in connection with the filing of this paper, including extension of time fees, to Deposit Account 500417 and please credit any excess fees to such deposit account.

Respectfully submitted,

MCDERMOTT, WILL & EMERY


Stephen A. Becker
Registration No. 26,527

600 13th Street, N.W.
Washington, DC 20005-3096
(202) 756-8000 SAB:tlb
Facsimile: (202) 756-8087
Date: December 3, 2003

INFORMATION DISCLOSURE CITATION IN AN APPLICATION		ATTY. DOCKET NO. 67161-134		SERIAL NO.		
		APPLICANT Koyu ASAI, et al.				
(PTO-1449)		FILING DATE December 03, 2003		GROUP		
U.S. PATENT DOCUMENTS						
EXAMINER'S INITIALS	CITE NO.	Document Number Number-Kind Code ² (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	
		US				
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FOREIGN PATENT DOCUMENTS						
EXAMINER'S INITIALS	CITE NO.	Foreign Patent Document Country Codes - Number & Kind Codes (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines Where Relevant Figures Appear	Translation Yes No
		JP 7-106323	04/21/1995	NEC CORP		(Japan w/English Abstract)
		JP 9-213800	08/15/1997	NEC CORP		(Japan w/English Abstract)
		JP 8-264647	10/11/1996	FUJITSU LTD		(Japan w/English Abstract)
OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)						
EXAMINER'S INITIALS	CITE NO.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.				
		"Stress-Induced Voiding Under Vias Connected to Wide Cu Metal Leads", E.T. Ogawa et al., 2002 IEEE International Reliability Physics Symposium Proceedings, April 7-11, 2002.				
		"Mechanisms of Stress-Induced Voids in Multi-Level Cu Interconnects", Byung-Lyul Park et al., IEEE 2002 International Interconnect Technology Conference, June 3-5, 2002.				
		"Thermal Stress of 140nm-width Cu damascene interconnects", Norio Okada et al., IEEE 2002 International Interconnect Technology Conference, June 3-5, 2002.				
EXAMINER			DATE CONSIDERED			

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

1 Applicant's unique citation designation number (optional). 2 Applicant is to place a check mark here if English language Translation is attached.